



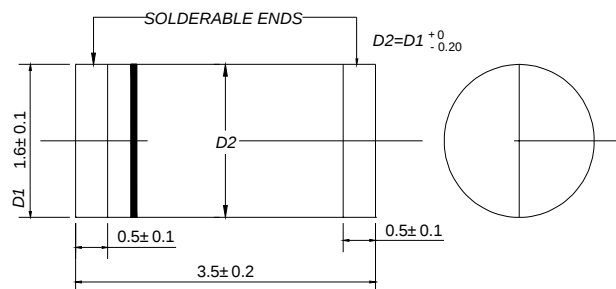
VOLTAGE RANGE: 50 --- 600 V
FORWARD CURRENT: 1.0 A



Features

Plastic package has underwriters laboratories
 flammability classification 94V-0
 Glass passivated chip junction
 For surface mount applications
 High temperature metallurgically bonded construction
 Cavity-free glass passivated junction
 High temperature soldering guaranteed:450 /5 seconds
 at terminals.Complete device sub-mersible temperature
 of 265 for 10 seconds in solder bath

DO - 213AA



Dimensions in millimeters

Mechanical Data

Case: JEDEC DO-213AA,molded plastic
 Polarity: Color band denotes cathode
 Weight: 0.0014 ounces, 0.036 grams
 Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified.

Single phase,half wave,60 Hz,resistive or inductive load. For capacitive load,derate current by 20%.

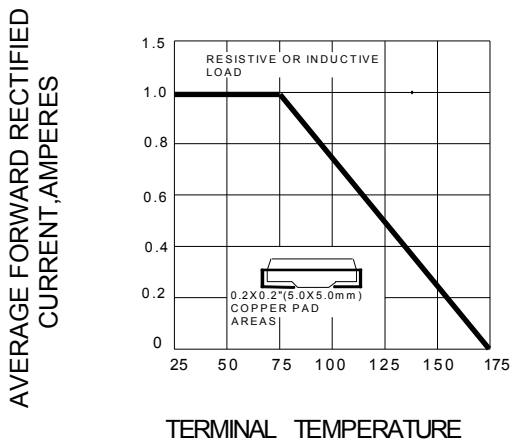
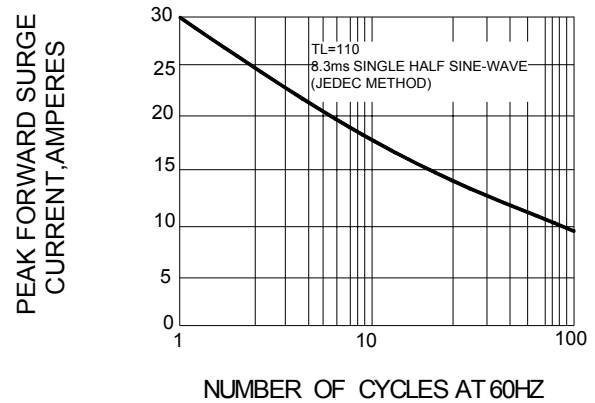
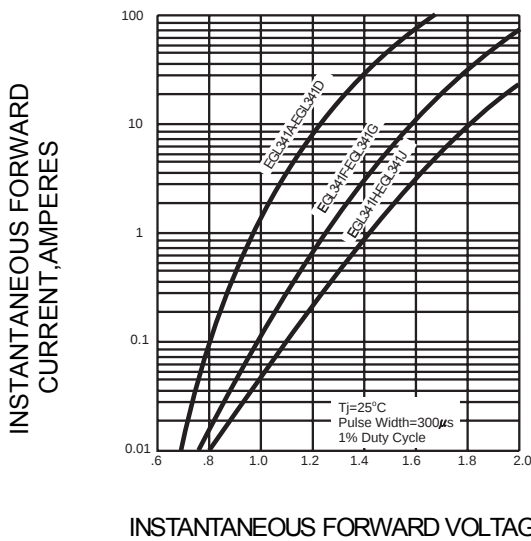
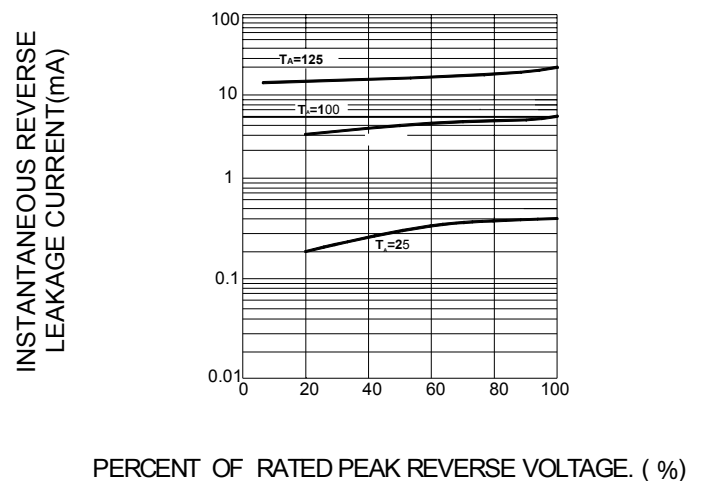
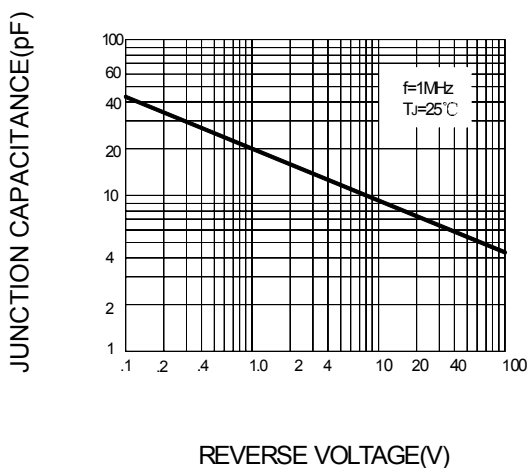
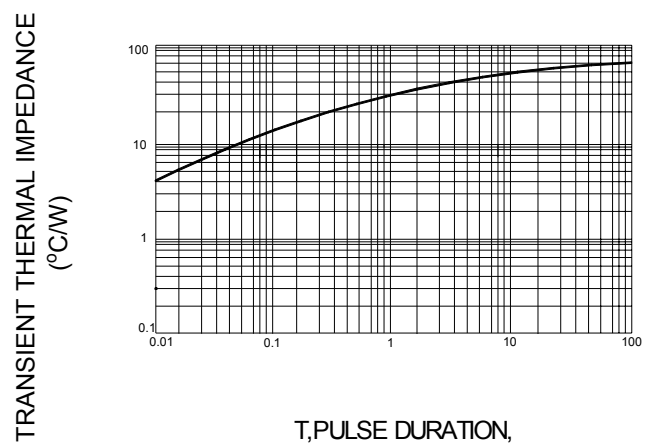
Type Number	Symbol	EGL 341A	EGL 341B	EGL 341D	EGL 341F	EGL 341G	EGL 341H	EGL 341J	UNITS
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	300	400	500	600	V
Maximum RMS voltage	V _{RMS}	35	70	140	210	280	350	420	V
Maximum DC blocking voltage	V _{DC}	50	100	200	300	400	500	600	V
Maximum average forward rectified current T _T =75	I _(AV)	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V _F	1.25			1.35		1.70		V
Maximum reverse current @T _A =25 at rated DC blocking voltage @T _A =125	I _R	5.0 50							μA
Maximum reverse recovery time (Note 1)	t _{rr}	35							ns
Typical junction capacitance (Note 2)	C _j	15							pF
Typical thermal resistance (Note 3)	R _{θJA}	150							K/W
Operating junction temperature range	T _j	- 55 ---- +175							
Storage temperature range	T _{STG}	- 55 ---- +175							

NOTE: 1. Measured with $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$

2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24×0.24"(6.0×6.0mm) copper pads to each terminal.

Ratings AND Characteristic Curves

FIG.1 – FORWARD CURRENT DERATING CURV

FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

FIG.5 – TYPICAL JUNCTION CAPACITANCE

FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE


PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-213AA	5000/REEL	80000	36.0X35.8X36.5	18.00	16.00